



## Reliable underfill inspection

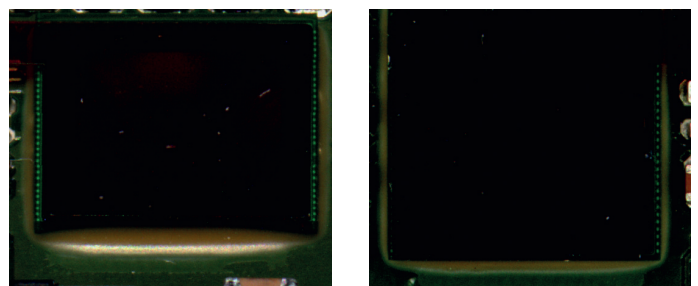
The inspection system S3088 UFI was developed specifically for reliable, cost-effective defect detection and fast process optimization. A versatile inspection concept with scalable, modular camera technology enables dependable inspection of underfillings of BGAs, Flip Chips and other components – from prototypes up to large series. By feeding electronic assemblies in and out at the same time, the Viscom FastFlow Handling ensures extremely short handling times down to a minimum of 2.5 seconds. Orthogonal cameras with a high resolution of up to 11.75  $\mu\text{m}/\text{pixel}$  guarantee consistently accurate detection even of critical defects, supported by optional side cameras with an 8  $\mu\text{m}/\text{pixel}$  resolution.

Another intelligent feature of Viscom AOI is the integrated defect verification. This feature ensures full defect detection even as it improves first pass yield. This gives system operators a convenient tool to back up a zero-escape strategy. Powerful add-on modules like off-line programming and SPC evaluation further enhance this offer.

**Quick and easy inspection program generation**

**Viscom FastFlow Handling for extremely high throughput**

**High performance underfill inspection**

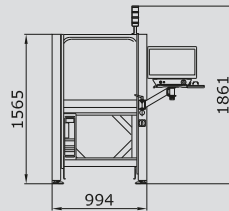


Different underfill features (bright)

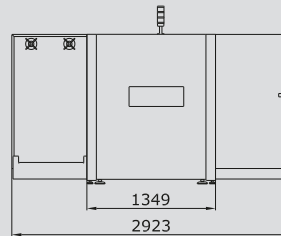
# Technical Specifications



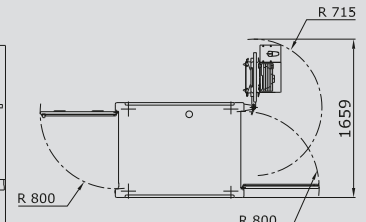
Front view



Side view



Top view



Dimensions in mm

		S3088 UFI
<b>Inspection scope</b>		Underfill inspection (optional: selective soldering, full-surface wave soldering, assembly inspection)
	<b>Camera technology</b>	<b>8M orthogonal camera module</b> Image field size: 57.6 mm x 43.5 mm (2.3" x 1.7") Resolution: 11.75 µm Number of megapixel cameras: 4  <b>8M angular view module (optional)</b> Resolution: 8 µm Number of megapixel cameras: 4 or 8
<b>Software</b>	User interface	Viscom EasyPro/vVision
	SPC	Viscom SPC (statistical process control), open interface (optional)
	Verification station	Viscom HARAN/vVerify
	Remote Diagnosis	Viscom SRC (optional)
	Programming station	Viscom PST34 (optional)
<b>System computer</b>	Operating system	Windows®
	Processor	Intel® Core™ i7
<b>PCB handling</b>	PCB dimensions	508 mm x 508 mm (20" x 20") (L x W)
	Transport height	900 - 950 mm ± 20 mm (35.4" - 37.4" ± 0.8")
	Width adjustment	Automatic during setup
	Transport concept	Single track transport
	PCB clamping	Pneumatic
	Upper transport clearance	50 mm (2")
	Lower transport clearance	60 mm (2.4")
<b>Inspection speed</b>		20 - 40 cm <sup>2</sup> /s
<b>Other system data</b>	Positioning/handling unit	Synchronous linear motors
	Interfaces	SMEMA
	Power requirements	230 V (other voltages on request), 1P/N/PE, 10 A
	System dimensions	994 mm x 1565 mm x 1349 mm (39.1" x 61.6" x 53.1") (W x H x D)
	Weight	600 kg (1323 lbs)

Subject to technical changes. Windows® and Intel® Core™ i7 are registered trademarks.